# PRODUCT / PROCESS CHANGE INFORMATION

## 1. PCI basic data

| | |
|---|---|
| **1.1 Company** | STMicroelectronics International N.V |
| **1.2 PCI No.** | CRP/22/13680 |
| **1.3 Title of PCI** | NEW 12” WAFERS FAB (AG300) IN AGRATE AVAILABLE FOR PRODUCTION (EARLY NOTIFICATION) |
| **1.4 Product Category** | see list |
| **1.5 Issue date** | 2022-09-29 |

## 2. PCI Team

| | |
|---|---|
| **2.1 Contact supplier** | |
| **2.1.1 Name** | KRAUSE INA |
| **2.1.2 Phone** | +49 89460062370 |
| **2.1.3 Email** | ina.krause@st.com |
| **2.2 Change responsibility** | |
| **2.2.1 Process Owner** | Delphine MAURY |
| **2.1.2 Corporate Quality Manager** | Gerard PETIT |

## 3. Change

| 3.1 Category | 3.2 Type of change | 3.3 Manufacturing Location |
|---|---|---|
| Transfer | Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Wafer fabrication | ST Crolles300 (Crolles / France)<br>ST AG300 (Agrate / Italia) |

## 4. Description of change

| | Old | New |
|---|---|---|
| **4.1 Description** | ST Crolles300 (Crolles / France) Diffusion Plant | ST Crolles300 (Crolles / France) Diffusion Plant and ST AG300 (Agrate) / Italia) Diffusion Plants |
| **4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?** | Form : no impact<br>Fit : no impact<br>Function : no impact<br>Reliability : no impact<br>Processability : no impact | |

## 5. Reason / motivation for change

| | |
|---|---|
| **5.1 Motivation** | Expansion of current silicon diffusion capability to both provide additional capacity and additional sourcing flexibility |
| **5.2 Customer Benefit** | CAPACITY INCREASE |

## 6. Marking of parts / traceability of change

| | |
|---|---|
| **6.1 Description** | Dedicated Finished Good codes |

## 7. Timing / schedule

| | |
|---|---|
| **7.1 Date of qualification results** | 2023-04-28 |
| **7.2 Intended start of delivery** | 2023-05-31 |
| **7.3 Qualification sample available?** | Upon Request |

## 8. Qualification / Validation

| | | | |
|---|---|---|---|
| **8.1 Description** | | | |
| **8.2 Qualification report and qualification results** | In progress | **Issue Date** | |

## 9. Attachments (additional documentations)

13680 Public product.pdf
13680 PCI AG300 FAB_Early Notification_rev3_W39.pdf

## 10. Affected parts

| 10. 1 Current | | 10.2 New (if applicable) |
|---|---|---|
| **10.1.1 Customer Part No** | **10.1.2 Supplier Part No** | **10.1.2 Supplier Part No** |
| 3021466 | LIS2DTW12TR | |
| 2980893 | IIS2DLPCTR | |
| | ILPS22QSTR | |
| | LPS22DFTR | |
| | LPS28DFWTR | |
| 2980917 | LSM6DSOTR | |
| 3011638 | LSM6DSOXTR | |

**IMPORTANT NOTICE – PLEASE READ CAREFULLY**

Subject to any contractual arrangement in force with you or to any industry standard implemented by us, STMicroelectronics NV and its subsidiaries (“ST”) reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST’s terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers’ products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2018 STMicroelectronics – All rights reserved